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J. W. H.  
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

Kenichi HAMANAKA, et al.

Date: August 23, 2002

Serial No.: 09/854,767

Group Art Unit: 2832

Filed: May 14, 2001

Examiner: J. A. Poker

For: ADHESIVE RESIN COMPOSITION AND METHOD  
OF PRODUCING THE SAME, AND CHIP COIL COMPONENT

Asst. Commissioner for Patents  
Washington, D.C. 20231

RESPONSE TO RESTRICTION REQUIREMENT

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In response to the restriction requirement mailed July 25, 2002, Applicants select Group I (claims 1-5) with traverse.

The division between Groups I and II has been justified on the grounds that the adhesive resin could be made by mixing ferrite powder with a cured matrix resin. It is not seen how this can be done and achieve an adhesive resin composition. Further, the classification of Groups I and II are both class 524, subclass 430. This reconfirms that the inventions are sufficiently related as to be processed in a single application.

Withdrawal of the restriction requirement to the extent it separates claims 1-5 from claims 6 and 7 is respectfully requested.

The early further examination and allowance of this application is respectfully solicited.

Respectfully submitted,

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